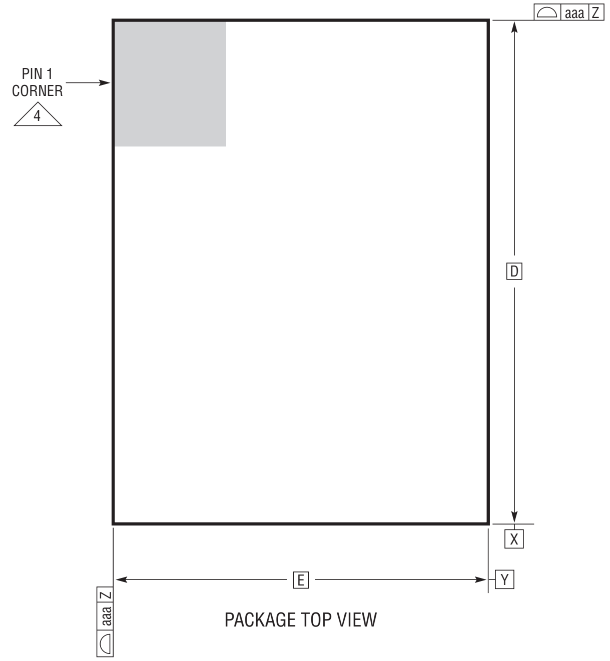
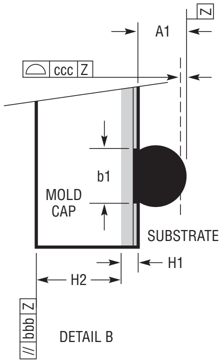
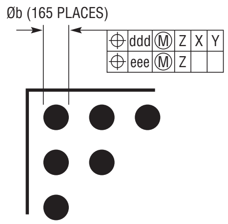
BGA Package
165-Lead (11.9mm × 16mm × 4.82mm)
(Reference LTC DWG # 05-08-7087 Rev 0)



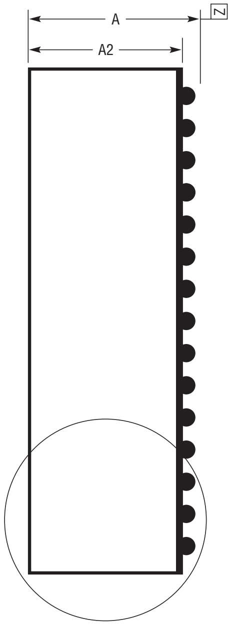
PACKAGE TOP VIEW



DETAIL B

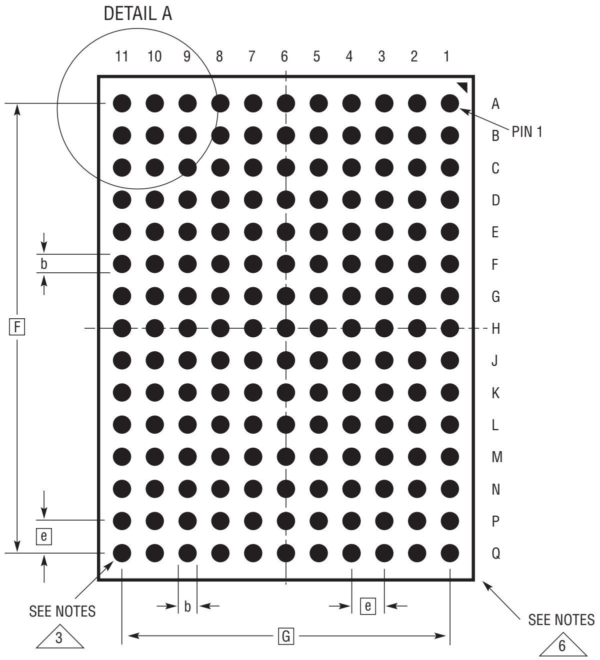


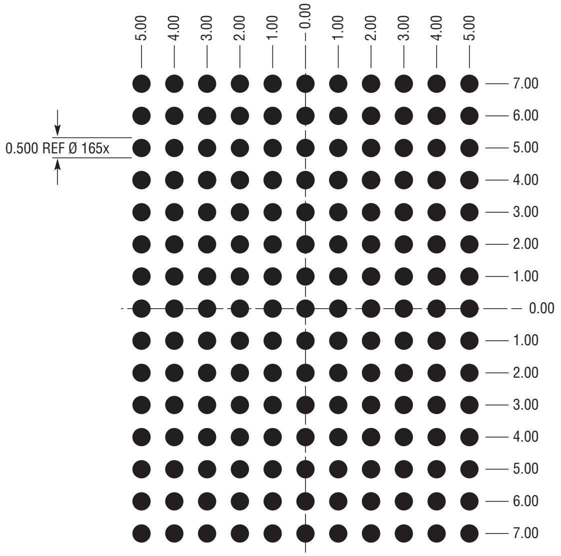
DETAIL A



DETAIL B

PACKAGE SIDE VIEW





SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	**MIN**	**NOM**	**MAX**	**NOTES**
A	4.62	4.82	5.02	
A1	0.40	0.50	0.60	BALL HT
A2	4.22	4.32	4.42	
b	0.50	0.60	0.70	BALL DIMENSION
b1	0.47	0.50	0.53	PAD DIMENSION
D		16.00		
E		11.90		
e		1.00		
F		13.00		
G		10.00		
H1		0.32 REF		SUBSTRATE THK
H2		4.00 REF		MOLD CAP HT
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.25	
eee			0.10	
TOTAL NUMBER OF BALLS: 165				

NOTES:

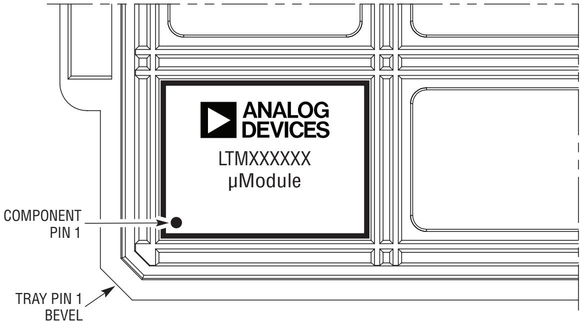
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS. DRAWING NOT TO SCALE

3 BALL DESIGNATION PER JEP95

4 DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE

5. PRIMARY DATUM -Z- IS SEATING PLANE

6 ⚠ PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION

BGA 165 0221 REV 0